



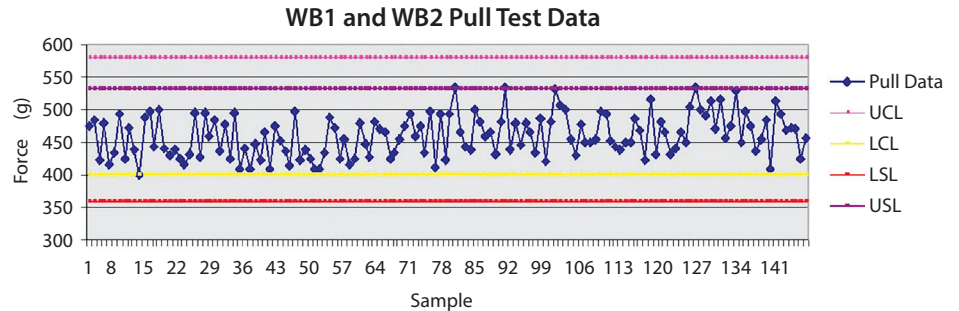
Quality Management Systems in the Microelectronic Assembly Business

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THERE ARE MANY QUALITY MANAGEMENT systems (QMS) that are used in the micro-electronic assembly business, too many to list them all here. AS9100 is for aerospace, IATF for automotive, ISO13485 for medical, ISO17025 for calibration and test labs, just to mention a few. Most of these standards are based on the ISO9001 QMS, and for good reason—ISO 9001 is viewed by most people as the minimum table stakes of good business practice. At SMART Microsystems, we have chosen to be ISO 9001-2015 registered, completing our eighth annual reassessment external audit in November. Although ISO has gone through a lot of changes over the years, the guiding principles are still just plain common sense for the microelectronics assembly business. The seven ISO guiding principles are: customer focus, process approach, continuous improvement, evidence based decision making, leadership, engagement of people, relationship management.

Customer focus seems like a simple enough concept, but exactly how is it implemented in practice? We like to say that the “voice of the customer” is ever present in the beginning, the end, and everywhere in between in the internal processes of any work being performed. We also reach back to our customers to get feedback on their unique perspective of what they think of the work we have performed for them. We document the feedback and record it for future reference.

The process approach can be as simple or as complicated as we please. ISO 9001 does not dictate how an organization conducts business but requires that one can produce evidence of the process. At SMART we use a simple but effective method of tracking work in process. All work in process at SMART has a “traveler” document with it that contains all of the information needed to complete the work required for that job. This document then becomes a permanent record when the job is complete. In addition, all of the major activities that are customer related have a well documented process. Continuous improvement is a major focus of ISO 9001-2015. It is no longer adequate to simply demon-



SPC data for evidence based decision making

Document # 12345

System
X Subsystem
Component

Design Responsibility: Company X

Prepared by: BB

Key Dates: _____

FMEA Date (rev A) : 1/1/2018

Cave Teams

PROCESS FAILURE MODES AND EFFECTS (PROCESS FMEA)																			
Process Step/Function	Requirement	Potential Failure Mode	Potential Effect of Failure	S e r i o u s n e s s	C r i t i c i t y	Potential Cause(s) Mechanism(s) of Failure	Controls Prevention	Controls Detection	D i s t i n c t i v e f r e q u e n c y	A v e r a g e c o n s e q u e n c e s e v e n t r a t e	Recommended Action(s)	Responsibility	Actions Taken & Target Completion Date	S t a t u s	O u t s t a n d i n g	R e v i s i o n	P l a n n e d	N e x t	
Header Assembly																			
Operation 105: Kit Materials	Purpose: Provides all the proper materials for the build	Killed Wrong wire - Wire too small	Will not bond	4	Improper marking	Operator training, Process Specs, Machine Set Up/PMs	Bondor will not work, rev control software	2	32										
		Killed Wrong wire - Wire too large	Will not load in wire bonder	1	Improper marking or improper reading by operator	Not able to process	Worst feed in equipment	2	8										
		Killed Wrong wire - wrong material	Will not bond	4	Improper marking	Operator training, Process Specs, Machine Set Up/PMs	Bondor will not work, rev control software	2	32										
		Damaged Sense element	no or weak output	7	Improper handling	Operator training, Process Specs, Machine Set Up/PMs	FFT	3	63										
		Incorrect Number of Parts/Material	Cannot complete build	1	Operator error	Not able to process	not able to complete	5	5										
		Wrong Capillary killed	Will not bond wire properly	5	Improper marking or improper reading by operator	Operator training, Process Specs, Machine Set Up/PMs	Pull test	2	30										
		Incorrect adhesive	Will not bond wire properly	6	Improper marking or improper reading by operator	Operator training, Process Specs, Machine Set Up/PMs	Inspect	3	54										
Operation 110: Prep Adhesive	Transfer adhesive from primary container to 3rd dispenser syringe barrels	Material out of date	Poor adhesion or bondline thickness	7	Incorrect labeling	Scheduled inventory logging	Work instructions / transfer	5	70										
			Will not process in dispenser	3				5	45										
			Does not cure properly	5			Final test	3	75										
Operation 115: 100% Incoming Inspection	Purpose: Inspect hardware and die before assembly	Rejecting good material	Insufficient material to complete build	1	Operator or insufficient training	Work instructions and training	Visual inspection	8	24										

Example of PFMEA

strate what has been done through the year, but also how the organization has improved. What defined steps the organization is taking to improve. In our case, we conduct regular quality training of the entire staff to continuously improve our implementation of the QMS. We also perform regularly scheduled reviews of our processes and customer feedback at our scheduled management review meetings.

Evidence-based decision making is a process like any other. It takes a certain level of organizational discipline to establish and maintain the process. There are a lot of tools that are available to facilitate the effort, like DFMEA, PFMEA, SPC, design reviews, and DOE. We use all of these tools and some others, on a regular basis, to bring quantitative data to the decision-making process. The microelectronics assembly business is a very

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technical and detail-oriented business, so tools like a FMEA and DOE are a natural fit. Over time, these tools have become a staple of our business, it just so happens that they also fit the ISO evidence-based decision making model.

Leadership, engagement of people, and relationship management are all basic requirements of good and effective leadership in any business. In the new ISO 9001 standard there is a very real focus on the engagement of management. In fact, the quality representative position in an organization has been eliminated in the new standard. This is driving action and engagement to higher levels in the organization. This means that the executive level manager in the organization can no longer just push the requirements on to the quality representative, they must be engaged. This approach fosters a top-down effect that demonstrates to everyone in the organization that the top management is quality centric, and has real buy-in. I think that we can all agree that this is good for any organization.

When most people that have been in business for some time think of ISO compliance, they think of a lot of meaningless paperwork and painful audits. But this is quite simply not the case, because the current ISO compliance does not dictate the method you use, only the results. Having just completed our annual registration reassessment audit with no findings, we often get the question "how do you do that?". The answer is actually quite simple. As a microelectronics assembly business, we were ISO compliant long before we achieved ISO registration. In fact, internally as an orga-



nization, our audits are a nonevent because nothing changes, and no special preparation is required by the staff. We simply keep doing those things we have been doing all along. So, if your organization is doing all of the things that are required to be a good and customer focused business, you are already ISO compliant, so why not get credit for it and achieve registration. At SMART we use ISO registered suppliers, and we love to have ISO registered customers.

For more information about SMART services visit www.spiritelectronics.com.

William Boyce is the Engineering Manager at SMART Microsystems. He has served in senior engineering roles over the last 19 years with accomplishments that include manufactured automotive sensors. He is certified in EIT and Six Sigma Green Belt and is an industry recognized expert in AI wire bonding. Additionally, he designed and led the metrology lab and machine shop at Sensata. Mr. Boyce earned a Bachelor of Science in Engineering degree from the University of Rhode Island and has been a member of the IMAPS New England Chapter for over 15 years.

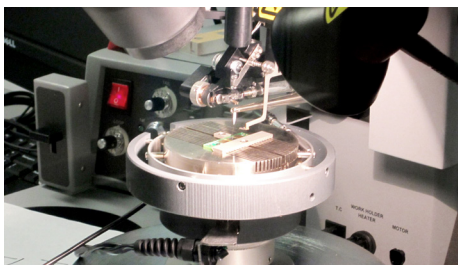
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